Infonote

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WLCSP MSL1 devices without HIC and desiccants

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Dear Customer,

please take note of this **Infonote**.

This customer notification is for information only and does not require customer approval.

Objective:	Wafer Level Packaging (WLCSP) MSL 1 (Moisture sensitivity level) vacuum packed devices under JEDEC without Humidity indicator card (HIC) and desiccants
Affected products:	see table below
Reason for change:	Increase efficiency of packing production step
Description of change:	From three (3) desiccants to zero (0) desiccant and removing HIC for 13” lokreel From two (2) desiccants to zero (0) desiccant and removing HIC for 7” lokreel
Time schedule:	April 2025
Assessment:	There will be no changes in terms of form, fit, function, quality or reliability

Material Number	Device Name	Q number
513890034	AS6221T-AWLT	Q65114A1340

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